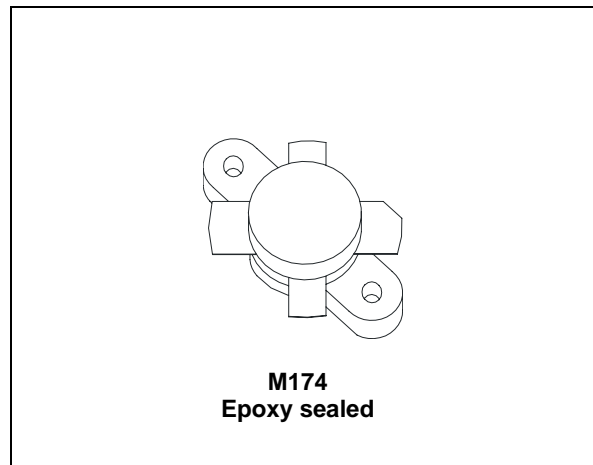


### Features

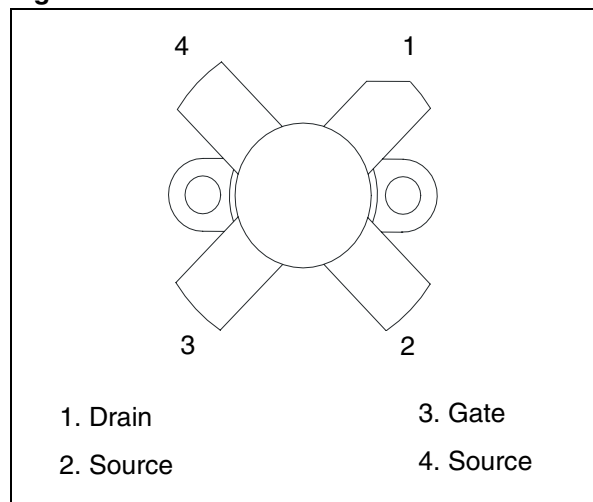
- Excellent thermal stability
- Common source configuration
- $P_{OUT} = 175\text{ W}$  min. with 23 dB gain @ 150 MHz
- In compliance with the 2002/95/EC European directive

### Description

The SD3931-10 is an N-channel MOS field-effect RF power transistor. It is intended for use in 100 V DC large signal applications up to 150 MHz.



**Figure 1. Pin connection**



**Table 1. Device summary**

Order code	Marking	Package	Packaging
SD3931-10	SD3931-10	M174	Plastic tray

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# Contents

<b>1</b>	<b>Electrical data</b> .....	<b>3</b>
1.1	Maximum ratings .....	3
1.2	Thermal data .....	3
<b>2</b>	<b>Electrical characteristics</b> .....	<b>4</b>
2.1	Static .....	4
2.2	Dynamic .....	4
<b>3</b>	<b>Impedance data</b> .....	<b>5</b>
<b>4</b>	<b>Typical performance</b> .....	<b>6</b>
<b>5</b>	<b>Test circuit</b> .....	<b>8</b>
<b>6</b>	<b>Circuit layout</b> .....	<b>9</b>
<b>7</b>	<b>Package mechanical data</b> .....	<b>10</b>
<b>8</b>	<b>Revision history</b> .....	<b>12</b>

# 1 Electrical data

## 1.1 Maximum ratings

**Table 2. Absolute maximum ratings ( $T_{CASE} = 25^{\circ}C$ )**

Symbol	Parameter	Value	Unit
$V_{(BR)DSS}^{(1)}$	Drain source voltage	250	V
$V_{DGR}$	Drain-gate voltage ( $R_{GS} = 1M\Omega$ )	250	V
$V_{GS}$	Gate-source voltage	$\pm 20$	V
$I_D$	Drain current	10	A
$P_{DISS}$	Power dissipation	389	W
$T_J$	Max. operating junction temperature	200	$^{\circ}C$
$T_{STG}$	Storage temperature	-65 to +150	$^{\circ}C$

1.  $T_J = 150^{\circ}C$

## 1.2 Thermal data

**Table 3. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thJC}$	Junction - case thermal resistance	0.45	$^{\circ}C/W$

## 2 Electrical characteristics

$$T_{\text{CASE}} = +25\text{ }^{\circ}\text{C}$$

### 2.1 Static

**Table 4. Static (per side)**

Symbol	Test conditions		Min	Typ	Max	Unit
$V_{(\text{BR})\text{DSS}}^{(1)}$	$V_{\text{GS}} = 0\text{ V}$	$I_{\text{DS}} = 100\text{ mA}$	250			V
$I_{\text{DSS}}$	$V_{\text{GS}} = 0\text{ V}$	$V_{\text{DS}} = 100\text{ V}$			1	mA
$I_{\text{GSS}}$	$V_{\text{GS}} = 20\text{ V}$	$V_{\text{DS}} = 0\text{ V}$			250	nA
$V_{\text{GS(Q)}}$	$V_{\text{DS}} = 10\text{ V}$	$I_{\text{D}} = 250\text{ mA}$	1.5	2.5	4.0	V
$V_{\text{DS(ON)}}$	$V_{\text{GS}} = 10\text{ V}$	$I_{\text{D}} = 5\text{ A}$		2.5	3.5	V
$G_{\text{FS}}$	$V_{\text{DS}} = 10\text{ V}$	$I_{\text{D}} = 2.5\text{ A}$	2.5			S
$C_{\text{ISS}}$	$V_{\text{GS}} = 0\text{ V}$	$V_{\text{DS}} = 100\text{ V}$		500		pF
$C_{\text{OSS}}$	$V_{\text{GS}} = 0\text{ V}$	$V_{\text{DS}} = 100\text{ V}$		134		pF
$C_{\text{RSS}}$	$V_{\text{GS}} = 0\text{ V}$	$V_{\text{DS}} = 100\text{ V}$		6		pF

1.  $T_{\text{J}} = 150^{\circ}\text{C}$

### 2.2 Dynamic

**Table 5. Dynamic**

Symbol	Test conditions		Min	Typ	Max	Unit
$P_{1\text{dB}}$	$V_{\text{DD}} = 100\text{ V}$	$I_{\text{DQ}} = 250\text{ mA}$ $f = 150\text{ MHz}$	175	230		W
$G_{\text{PS}}$	$V_{\text{DD}} = 100\text{ V}$	$I_{\text{DQ}} = 250\text{ mA}$ $P_{\text{OUT}} = 175\text{ W}$ $f = 150\text{ MHz}$	20	21.3		dB
$\eta_{\text{D}}$	$V_{\text{DD}} = 100\text{ V}$	$I_{\text{DQ}} = 250\text{ mA}$ $P_{\text{OUT}} = 175\text{ W}$ $f = 150\text{ MHz}$	50	57		%
Load mismatch	$V_{\text{DD}} = 100\text{ V}$	$I_{\text{DQ}} = 250\text{ mA}$ $P_{\text{OUT}} = 150\text{ W}$ $f = 150\text{ MHz}$ All phase angles	3:1			VSWR

### 3 Impedance data

Figure 2. Impedance data

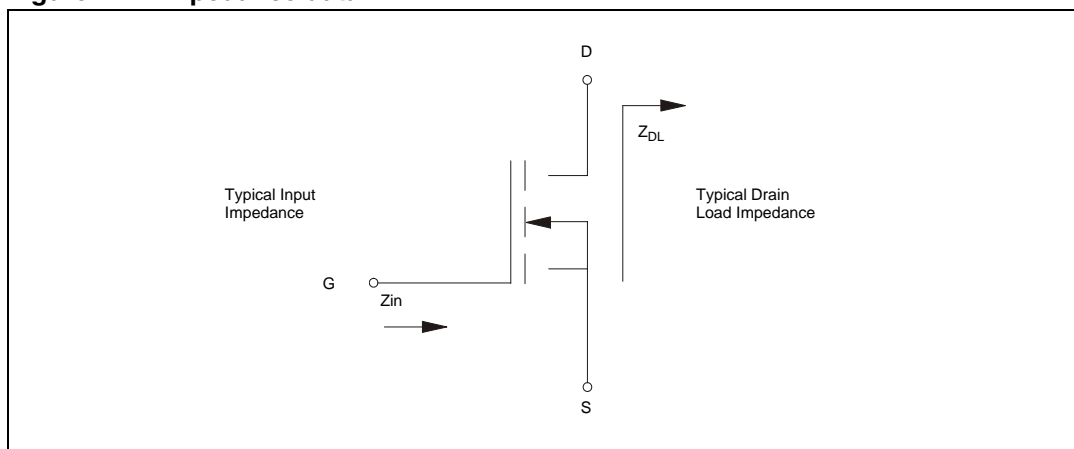


Table 6. Impedance data

Freq	$Z_{IN}$ ( $\Omega$ )	$Z_{DL}$ ( $\Omega$ )
150 MHz	$0.42 - j 3.1$	$3.4 + j 5.5$

# 4 Typical performance

Figure 3. Capacitances vs voltage

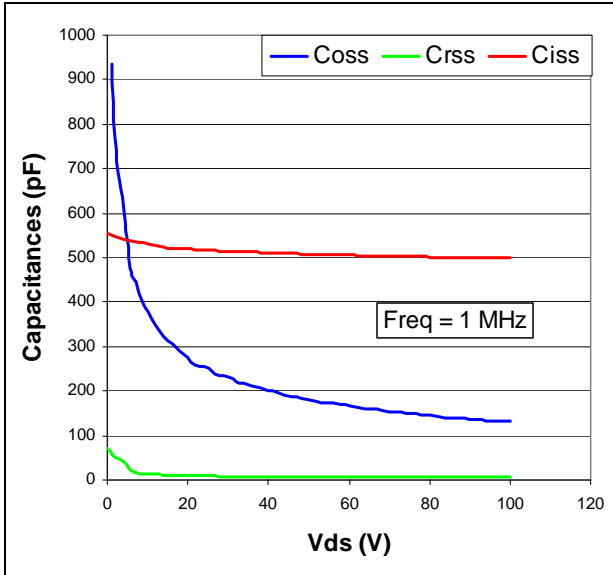


Figure 4. Gain vs output power and bias current

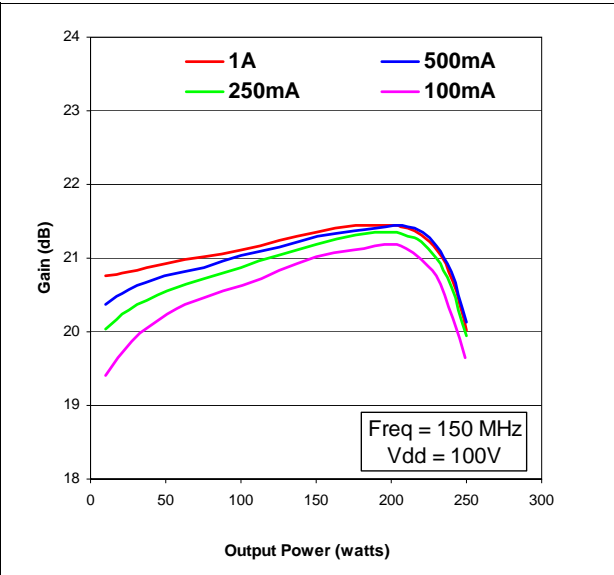


Figure 5. Output power and efficiency vs input power

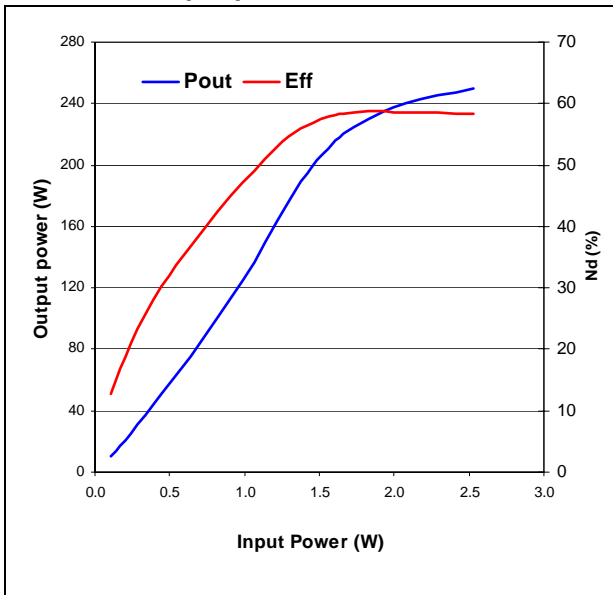
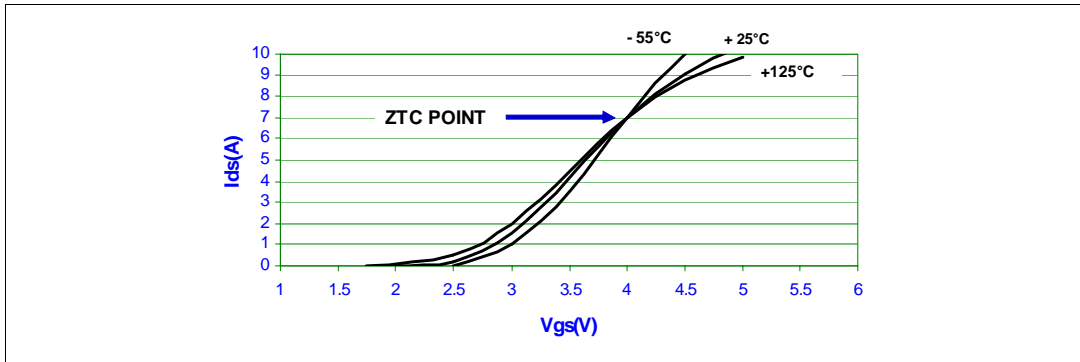


Figure 6. Zero temperature coefficient point

Table 7.  $V_{gs}$  sort (@250 mA)

Marking	Min	Max
DD	1.5	1.6
EE	1.6	1.7
FF	1.7	1.8
A	1.8	1.9
B	1.9	2
C	2	2.1
D	2.1	2.2
E	2.2	2.3
F	2.3	2.4
G	2.4	2.5
H	2.5	2.6
I	2.6	2.7
J	2.7	2.8
K	2.8	2.9
L	2.9	3
M	3	3.1
N	3.1	3.2
O	3.2	3.3
P	3.3	3.4
Q	3.4	3.5
R	3.5	3.6
S	3.6	3.7
T	3.7	3.8
U	3.8	3.9
V	3.9	4



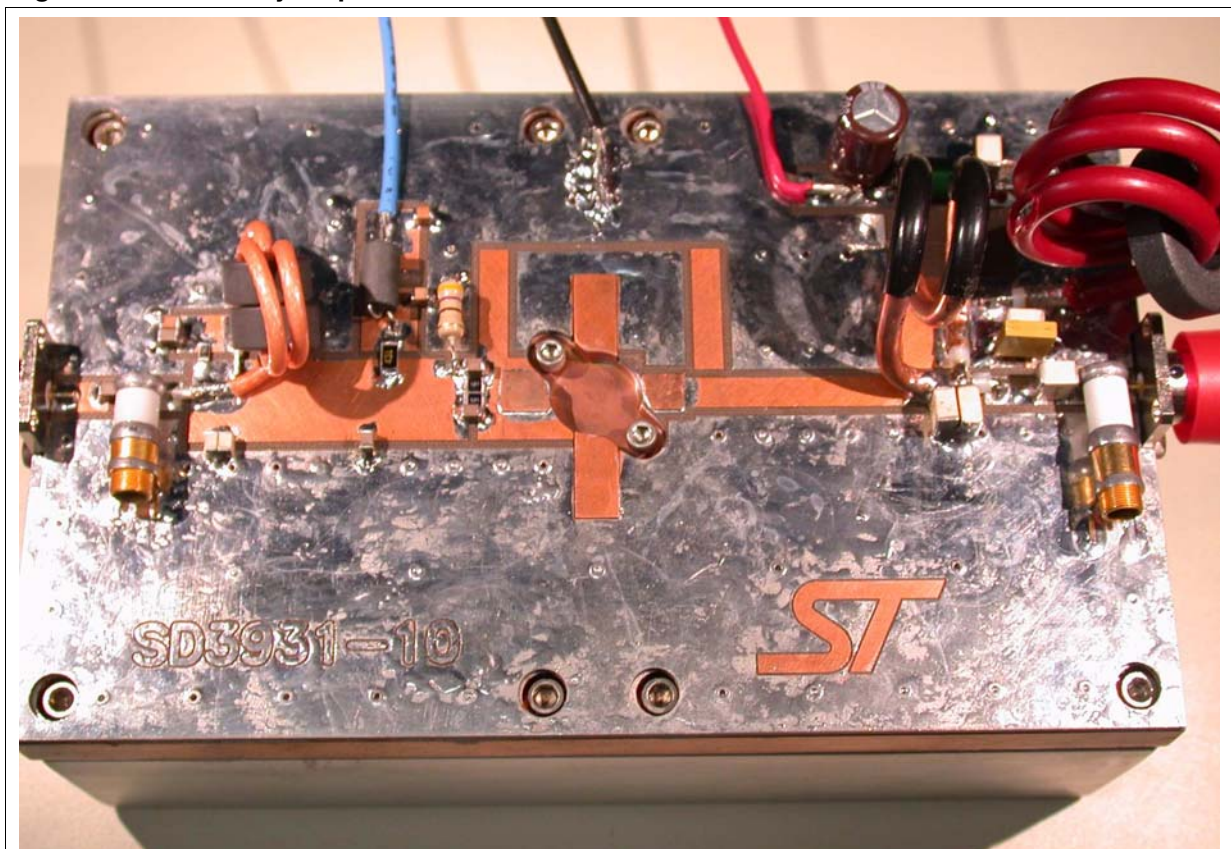


Table 8. Bill of materials (continued)

Component	Description
TL2	0.135" x 0.175" microstrip
TL3	0.225" x 0.175" microstrip
TL4	0.175" x 0.500" microstrip
TL5	0.805" x 0.500" microstrip
TL6	0.600" x 0.500" microstrip
TL7	0.420" x 0.500" microstrip
TL8	0.265" x 0.240" microstrip
TL9	1.550" x 0.180" microstrip
TL10	0.360" x 0.175" microstrip
TL11	0.300" x 0.175" microstrip
PCB	0.062" woven glass, copper clad, Er = 2.55

## 6 Circuit layout

Figure 8. Circuit layout photo



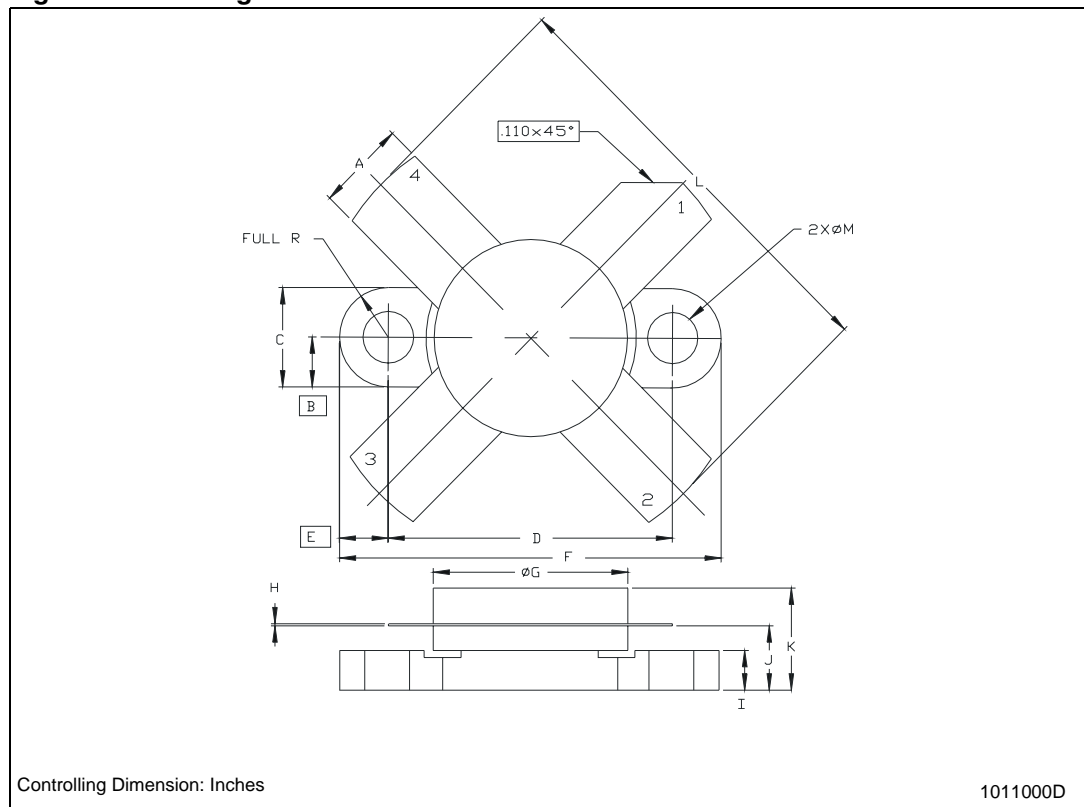
## 7 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. E COPACK<sup>®</sup> specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

**Table 9. M174 (0.500 DIA 4/L N/HERM W/FLG) mechanical data**

Dim.	mm.			Inch		
	Min	Typ	Max	Min	Typ	Max
A	5.56		5.584	0.219		0.230
B		3.18			0.125	
C	6.22		6.48	0.245		0.255
D	18.28		18.54	0.720		0.730
E		3.18			0.125	
F	24.64		24.89	0.970		0.980
G	12.57		12.83	0.495		0.505
H	0.08		0.18	0.003		0.007
I	2.11		3.00	0.083		0.118
J	3.81		4.45	0.150		0.175
K			7.11			0.280
L	25.53		26.67	1.005		1.050
M	3.05		3.30	0.120		0.130

**Figure 9. Package dimensions**



## 8 Revision history

**Table 10. Document revision history**

Date	Revision	Changes
15-Jun-2007	1	First release
11-Jul-2007	2	Inserted <a href="#">Table 7: Vgs sort (@250 mA) on page 7</a>
26-Oct-2007	3	Updated <a href="#">Table 4: Static (per side) on page 4</a> Added <a href="#">Section 5: Test circuit on page 8</a> , <a href="#">Section 6: Circuit layout on page 9</a>
11-Jul-2008	4	Updated <a href="#">Table 4: Static (per side) on page 4</a>
07-Sep-2010	5	Updated features on cover page.

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